





# Leveraging efficiency in automotive on-board chargers

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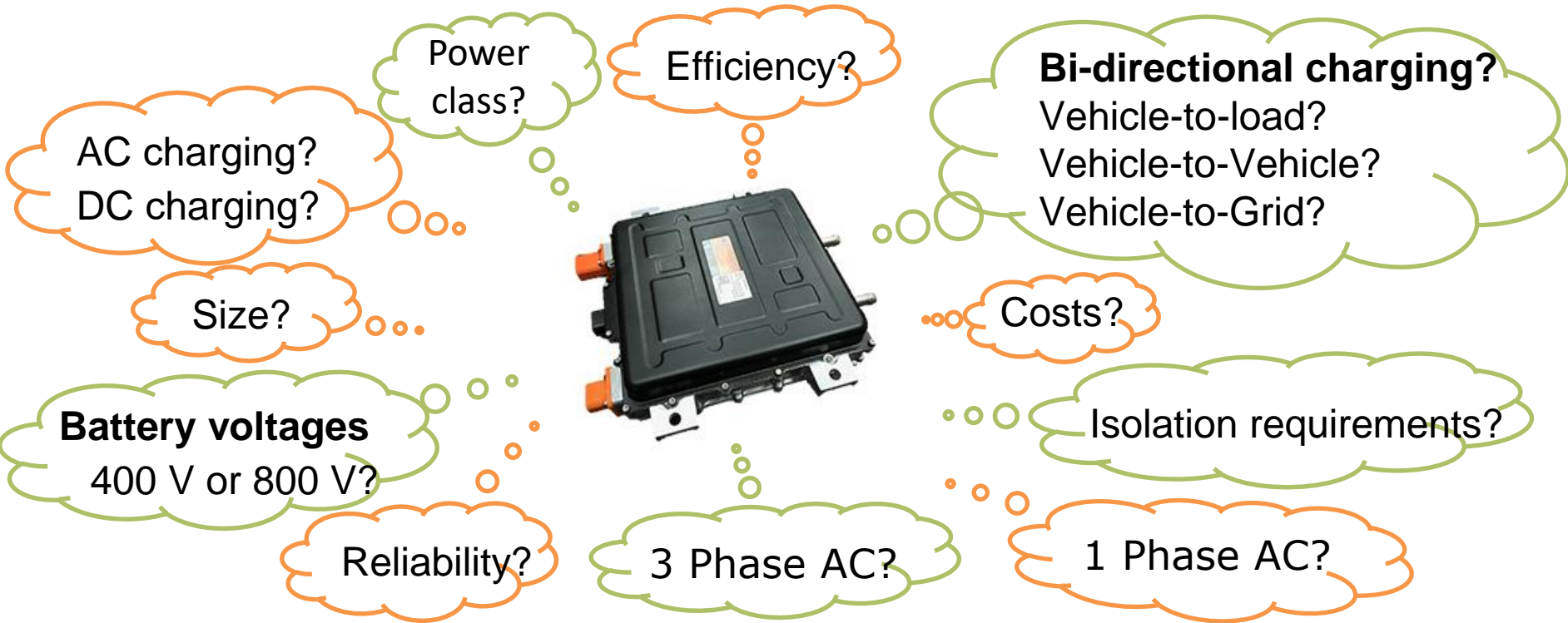
# Agenda

1	Introduction	
2	Single-phase chargers	
3	Three-phase chargers	
4	Case study and conclusion	

# Agenda

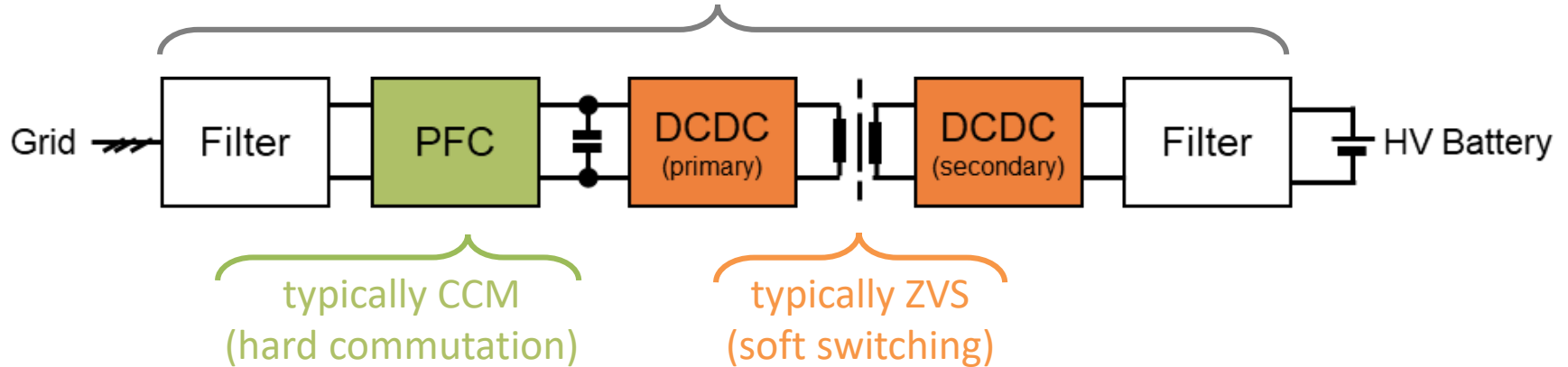
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# System requirements



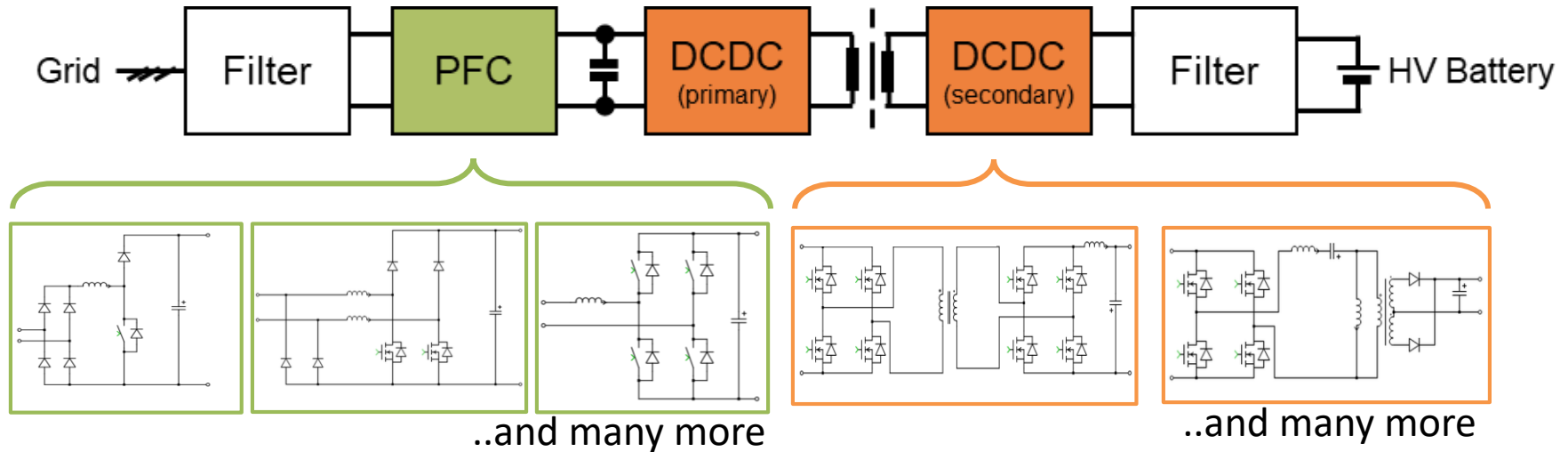
**The system has to cover many different requirements**

# OBC block diagram





**Typical OBCs are composed of a PFC block and an isolated DCDC block**

# Various topologies and semiconductor combinations possible



**Final implementation depends on required  
functionality**

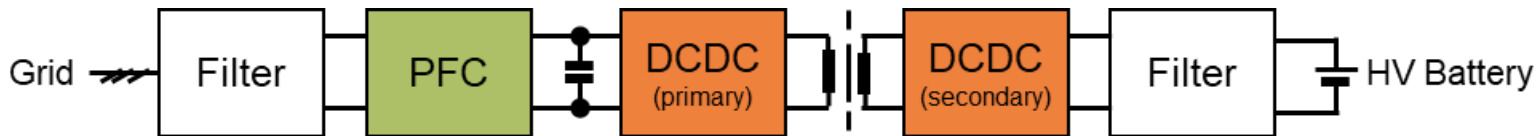
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1ph

# Classic-boost PFC



IGBT + PN D	IGBT + SiC D	CoolMOS™ + SiC D
97.9%	98.3%	98.4% (3pin) 98.5% (4pin)
1x PN diode 1x 650V IGBT with diode	1x 650 V SiC diode 1x 650 V IGBT with diode	1x 650 V SiC diode 1x 650 V CoolMOS™

efficiency increase

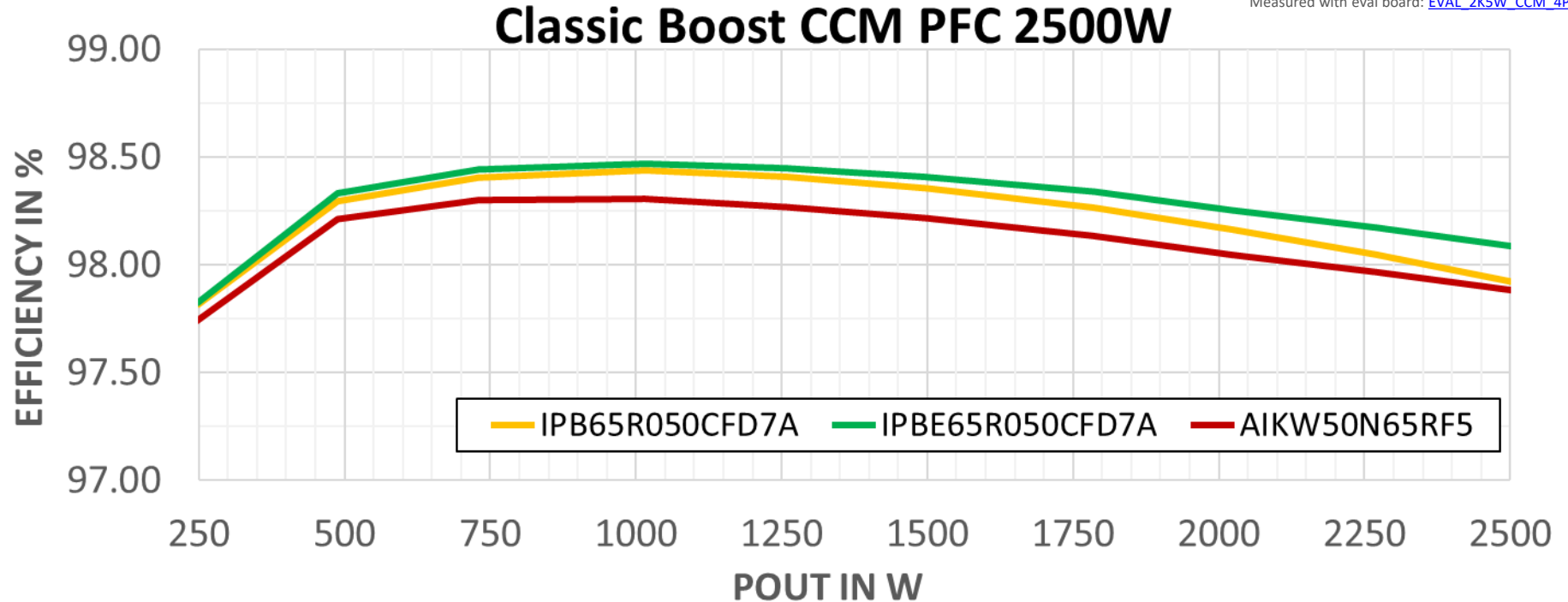
measured on [EVAL\\_2.5KW\\_CCM\\_4PIN](#)



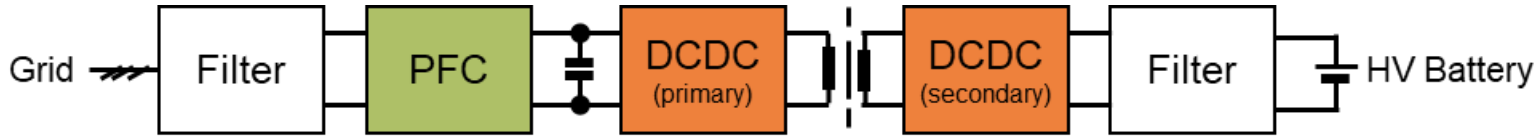
# Efficiency measurement



Measured with eval board: [EVAL\\_2K5W\\_CCM\\_4P\\_V3](#)



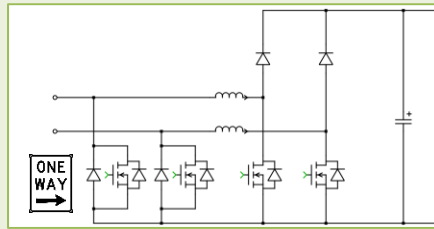
# Dual-boost (bridgeless) PFC



650 V CoolMOS™ + SiC D

98.6%

2x 650 V SiC Diode  
4x 650 V CoolMOS™  
2x PN diodes



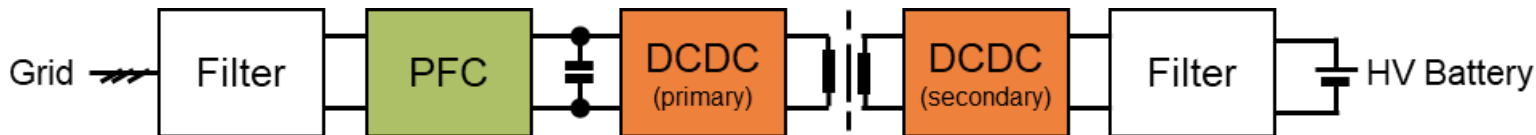
Very high efficiency

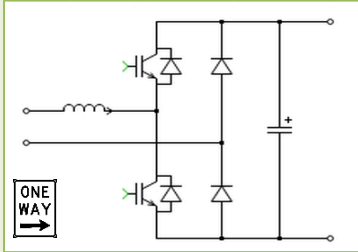
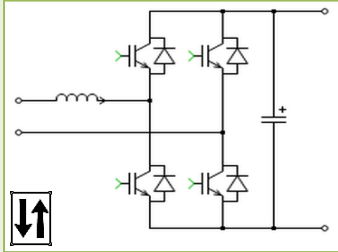
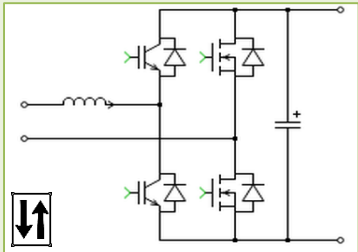
increased number of active  
switches



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# Totem Pole PFC

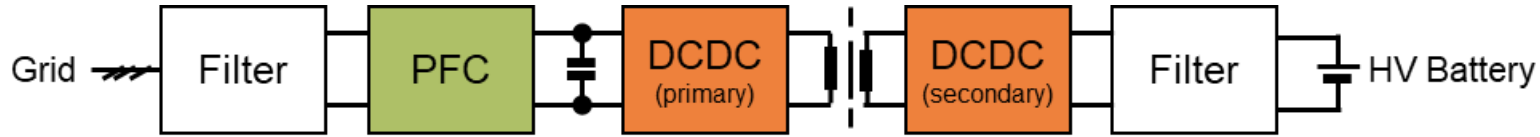


Half-bridge IGBT	Full-bridge IGBT	IGBT and CoolMOS™
98.7%	98.7%	98.8%
2x PN Diode 2x 650 V IGBT with diode	4x 650 V IGBT with diode	2x IGBT with diode 2x 650 V CoolMOS™ *)
		

\*) as long as hard commutation on the body diode is avoided

efficiency increase

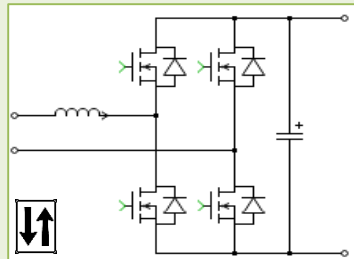
# TCM PFC (soft-switching)



650 V CoolMOS™ + SiC D

99.1%

> 4x 650 V CoolMOS™



Measured on [TCM\\_PFC](#)

Highest performance  
with Silicon devices

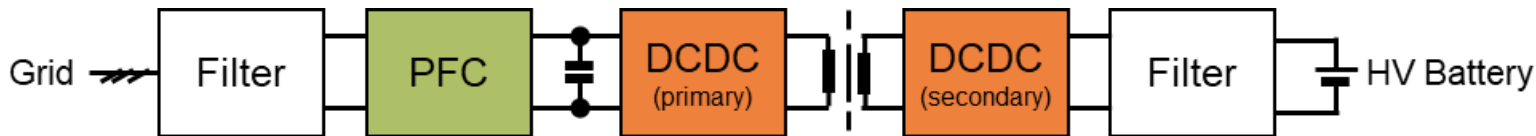
High control complexity

Interleaving required



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# DCDC (soft-switching)

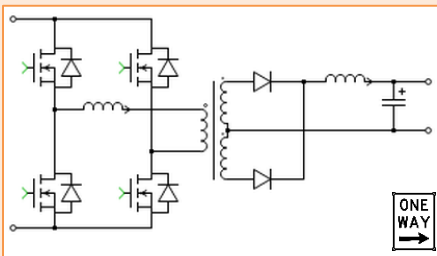


## Phase-shifted full-bridge

98.1%

4x 65 0V CoolMOS™

2x PN diodes (with ctr-tap)

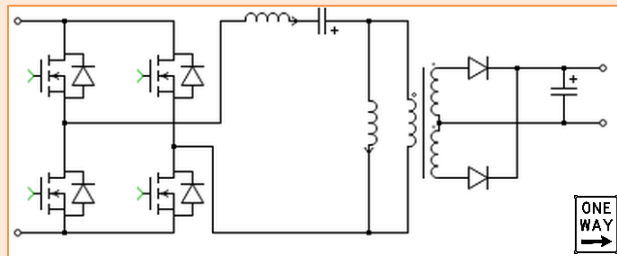


## Full-bridge LLC

98.5%

4x 650 V CoolMOS™

2x PN diodes (with ctr-tap)

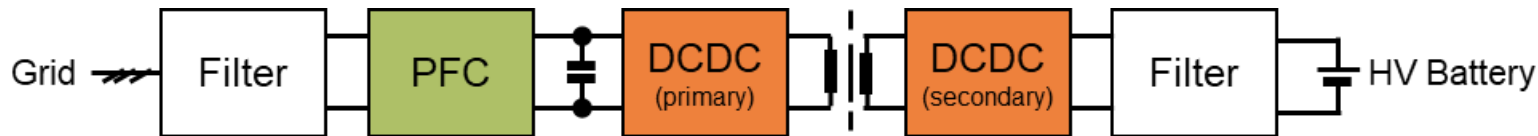


efficiency increase



1ph

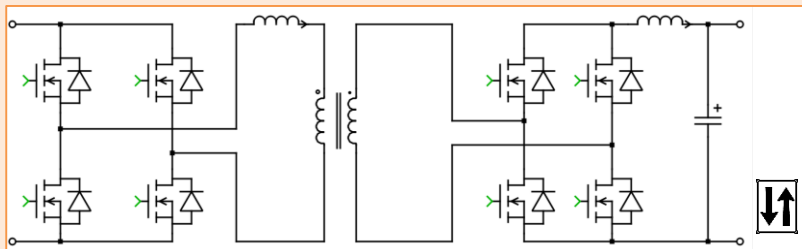
# DCDC (soft-switching)



## Phase-shifted full-bridge

98.1%

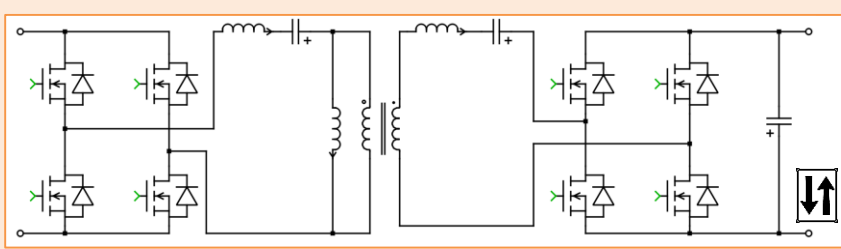
8x 650 V CoolMOS™



## Full-bridge cLLC



~98.3%

8x 650 V CoolMOS™



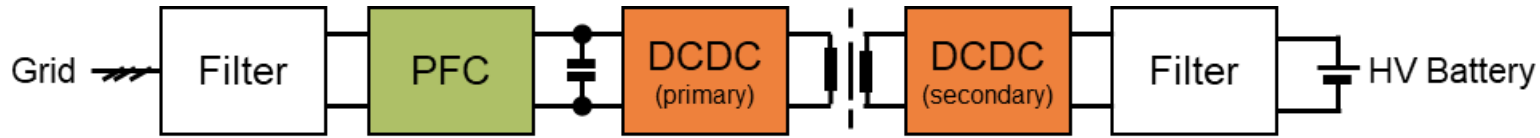
*efficiency increase*

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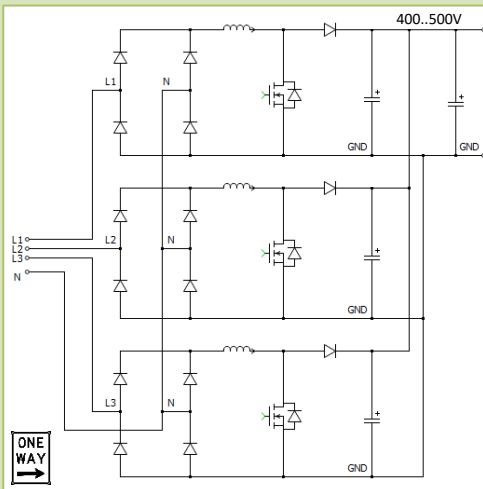
# Stacked PFC



## Stacked classic boost

12x PN Diodes  
3x 650 V SiC diode  
3x 650V  
CoolMOS™

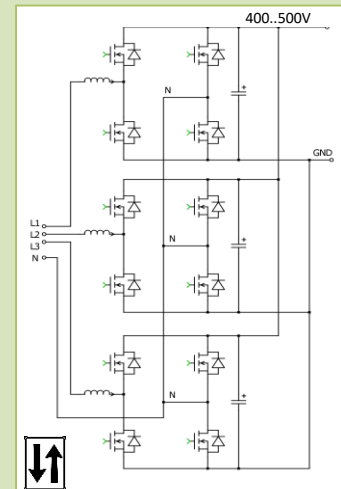
Alternatively:  
3x 650 V IGBT



## IGBT + SiC D

12x 650 V IGBT

Alternatively:  
6x 650 V IGBT  
6x 650 V CoolMOS™

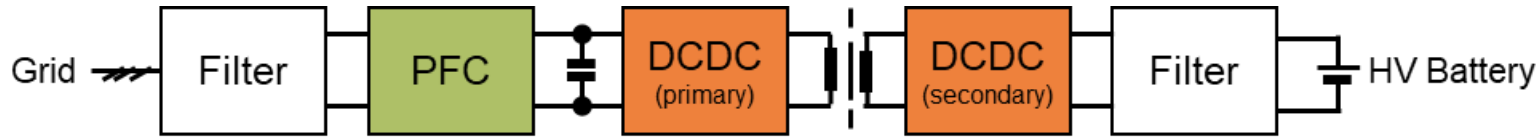


efficiency increase



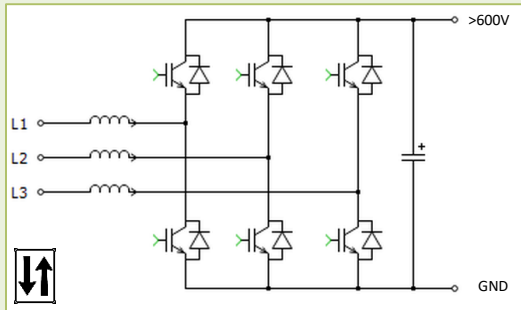


# PFC with higher DC-link



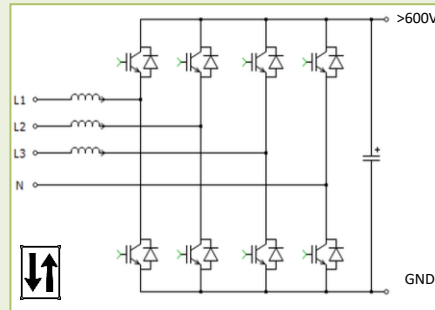
## 3ph full-bridge PFC

6x 1200 V SiC MOSFET



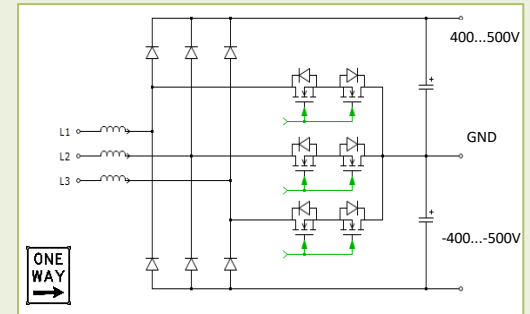
## 3ph full-bridge PFC + N

8x 1200 V SiC MOSFET

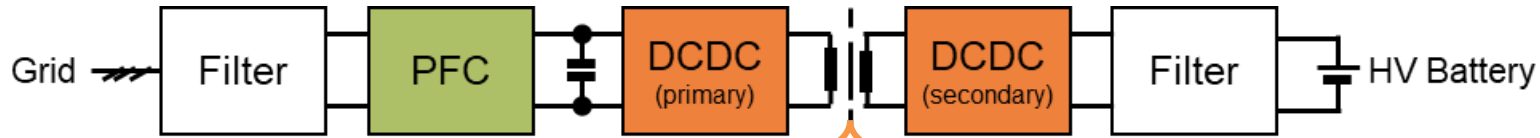


## Vienna Rectifier

6x 650 V IGBT or CoolMOS™  
6x 1200 V SiC Diode

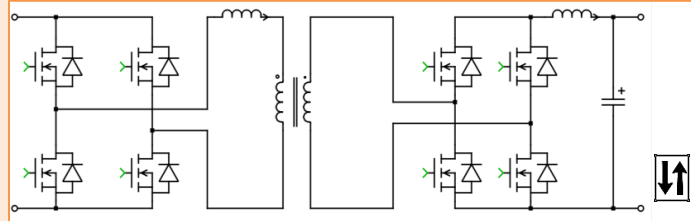


# DCDC for 3ph OBCs

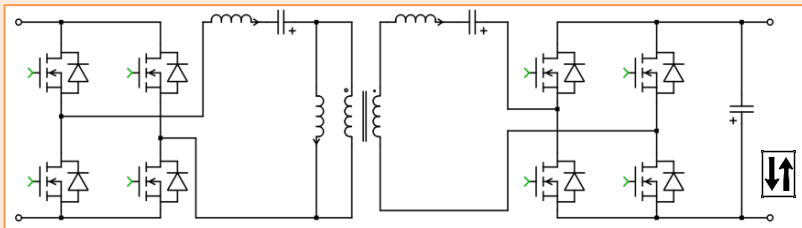


## Single-stage

PSFB:



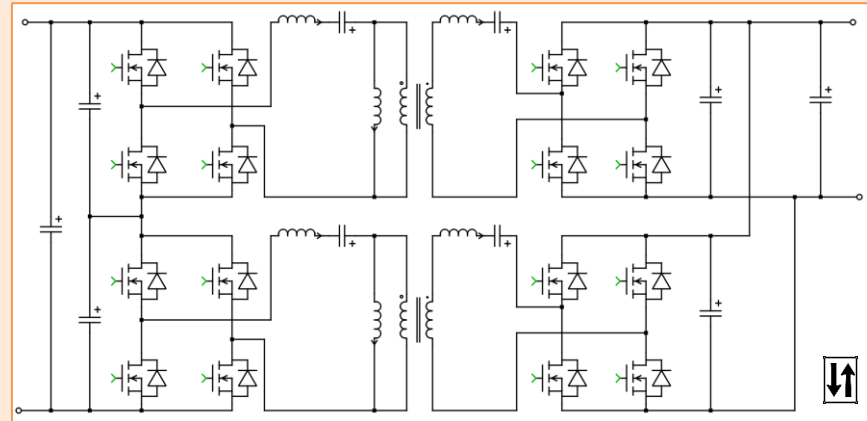
CLLC:



8x 1200 V SiC MOSFET



## Stacked DCDC

Stacked CLLC with split DC-link:



16x 650 V CoolMOS™

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# Case study: OBC efficiency today

EV	Charge standard	Charge power	Energy Efficiency		
			$\eta_3$	$\eta_{2,E}$	$\eta_{1,E}$
iOn	10 A @ 1 phase	2.3 kW	77 %	70 %	79 %
iOn	16 A @ 1 phase	3.7 kW	75 %	69 %	77 %
LEAF	10 A @ 1 phase	2.3 kW	74 %	85 %	
LEAF	16 A @ 1 phase	3.7 kW	70 %	90 %	
Zoe	10 A @ 1 phase	2.3 kW	49 %	Highest efficiency in their experiment	
Zoe	16 A @ 3 phase	11 kW	64 %		
Zoe	32 A @ 3 phase	22 kW	65 %		
Zoe	63 A @ 3 phase	43 kW	63 %		



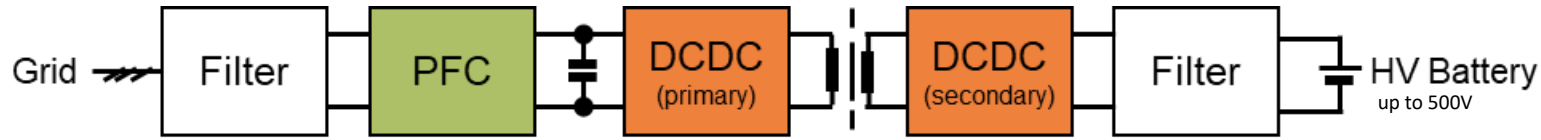
$$\rightarrow \eta_{\text{OBC\_max}} = 95\%$$



efficiency from typical OBC spec of today

**Source:** Kiildsen, Andreas; Thingvad, Andreas; Martinenas, Sergejus; Sørensen, Thomas Meier, *Proceedings of EVS29 - International Battery, Hybrid and Fuel Cell Electric Vehicle Symposium*, 2016.

**Today's OBCs require only moderate efficiency values**

# Which combinations do the job?



<div>  </div>			<div>  </div>			$\eta_{\text{req}} = 95\%$	
						$\eta_{\text{OBC}}$	ok?
Topology	Technology	$\eta$	Topology	Technology	$\eta$	$\eta_{\text{OBC}}$	ok?
Classic-boost	IGBT + SiC D	98.3%	PSFB	CoolMOS™	98.1%	96.4%	✓
Dual-boost	CoolMOS™ + SiC D	98.6%	LLC	CoolMOS™	98.5%	97.1%	✓
Totem-Pole	IGBT + CoolMOS™	98.8%	LLC	CoolMOS™	98.5%	97.3%	✓

**Smart topology choices with Silicon power devices do a great job!**

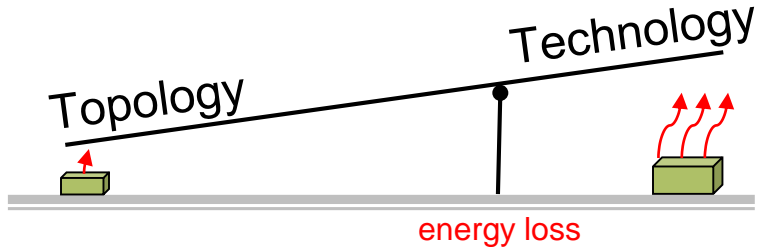
# Conclusion

Group Period	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18														
1	1 H																	2 He														
2	3 Li	4 Be											5 B	6 C	7 N	8 O	9 F	10 Ne														
3	11 Na	12 Mg											13 Al	14 Si	15 P	16 S	17 Cl	18 Ar														
4	19 K	20 Ca	21 Sc	22 Ti	23 V	24 Cr	25 Mn	26 Fe	27 Co	28 Ni	29 Cu	30 Zn	31 Ga	32 Ge	33 As	34 Se	35 Br	36 Kr														
5	37 Rb	38 Sr	39 Y	40 Zr	41 Nb	42 Mo	43 Tc	44 Ru	45 Rh	46 Pd	47 Ag	48 Cd	49 In	50 Sn	51 Sb	52 Te	53 I	54 Xe														
6	55 Cs	56 Ba	57 La	58 Ce	59 Pr	60 Nd	61 Pm	62 Sm	63 Eu	64 Gd	65 Tb	66 Dy	67 Ho	68 Er	69 Tm	70 Yb	71 Lu	72 Hf	73 Ta	74 W	75 Re	76 Os	77 Ir	78 Pt	79 Au	80 Hg	81 Tl	82 Pb	83 Bi	84 Po	85 At	86 Rn

Today's efficiency requirements are achievable with economic device choices

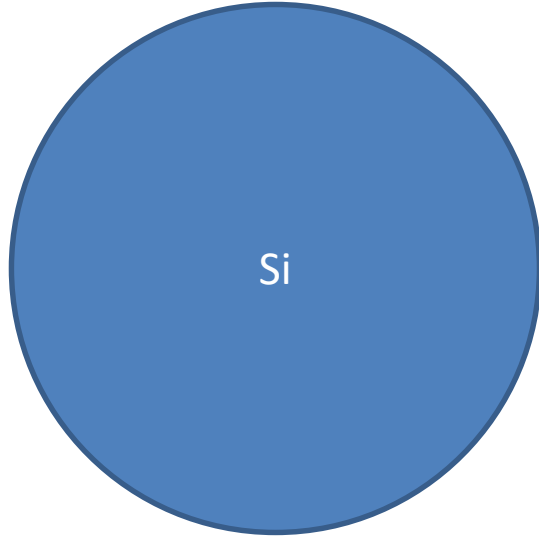
Stacking of single-phase topologies for 3phase systems allow usage of 650 V devices

Leverage efficiency by changing the topology (rather than just changing the power device technology)

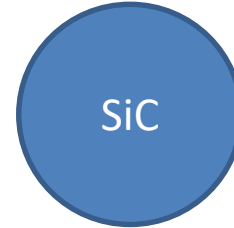


Backup slides

# Manufacturing



Lower manufacturing complexity  
Lower costs for base material  
20 years+ experience



Better Figure-of-Merits (for some parameters)  
Higher manufacturing complexity  
Higher costs for base material